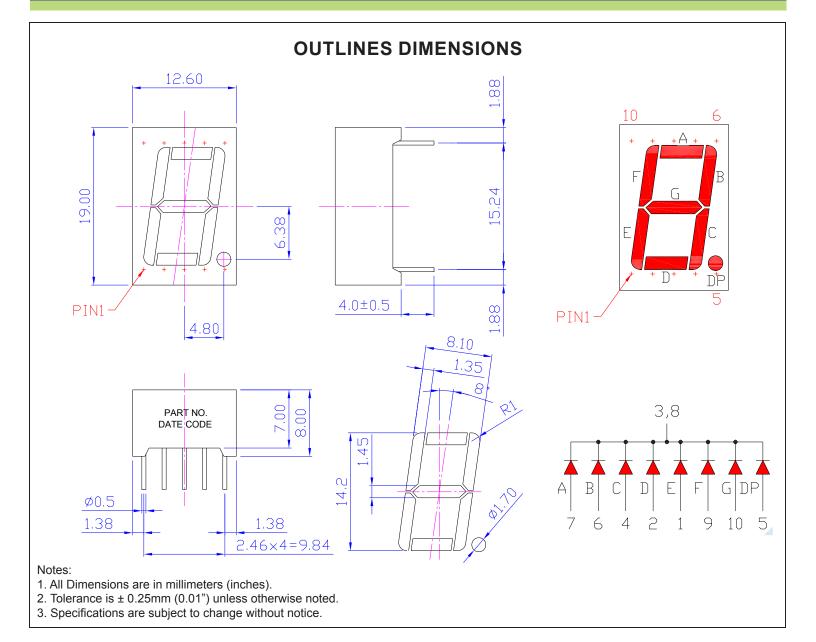


SPECIFICATIONS

CDSC56R2WB



Part Number	Chip Material	Color of Emission Segment/Face		Description	
CDSC56R2WB	InGaAIP	Red	White/Black	Common Cathode	





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit			
Power Dissipation	PD	70	mW			
Pulse Forward Current	lfp	90	mA			
Continuous Forward Current	lF	25	mA			
Reverse Voltage Segment	VR	5	V			
Operating Temperature Range	Topr	-25~+85	°C			
Storage Temperature Range	Тѕтс	-25~+85	°C			
IFP = Pulse Width \leq 10 ms, Duty Ratio \leq 1/10. Soldering Condition: 260 °C/ 5sec						

OPTICAL-ELECTRICAL CHARACTERISTICS

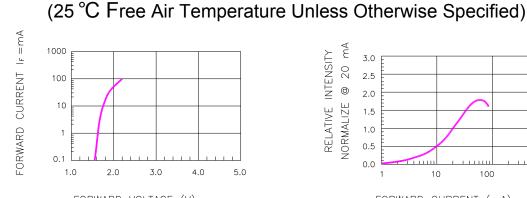
(TA=25°C)

Deremeter	Symbol	Test Condition	Value			Lloit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	lv	l⊧ = 10mA	11	-	17.6	mcd
Forward Voltage	Vf	l⊧ = 20mA	-	2.0	2.6	V
Reverse Leakage Current	lr	V _R = 5V	-	-	10	μA
Peak Wavelength	λP	l⊧ = 20mA	-	650	-	nm
Dominant Wavelength	λD	l⊧ = 20mA	636	640	646	nm
Spectral Radiation Bandwidth	Δλ	l⊧ = 20mA	-	20	-	nm





OPTICAL CHARACTERISTIC CURVES



FORWARD VOLTAGE (V) Fig.1 FORWARD CURRENT VS. FORWARD VOLTAGE

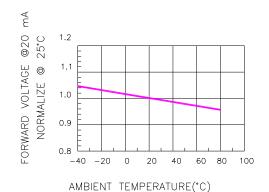
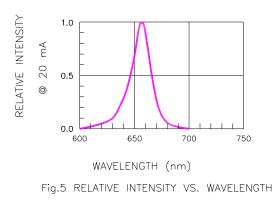
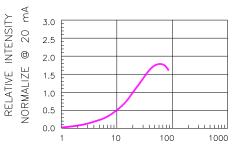
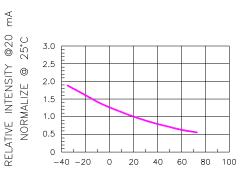


Fig.3 FORWARD VOLTAGE VS. TEMPERATURE

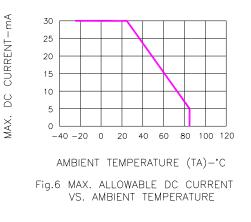




FORWARD CURRENT (mA) Fig.2 RELATIVE INTENSITY VS. FORWARD CURRENT



AMBIENT TEMPERATURE(°C) Fig.4 RELATIVE INTENSITY VS. TEMPERATURE

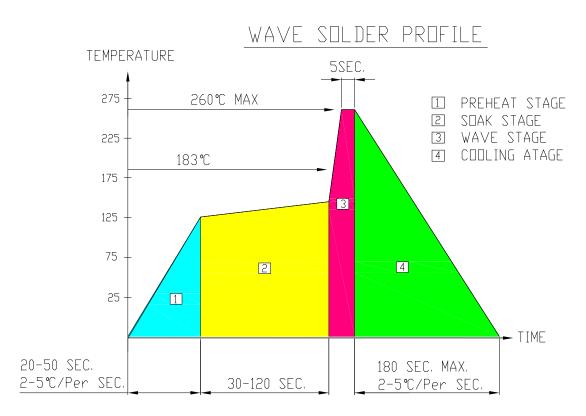






SOLDERING CONDITIONS – DISPLAY TYPE LED

RECOMMEND SOLDERING PROFILE



SOLDERING IRON

Basic spec is \leq 4 sec when 260°C. If temperature is higher, time should be shorter (+10°C→1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.

REWORK

Customer must finish rework within ≦4 sec under 245°C.

The head of soldering iron cannot touch copper foil.

